

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

[1] (Original) A module comprising:

a substrate; and

a plurality of semiconductor packages, each comprising a semiconductor chip, mounted on the substrate;

wherein each of the plurality of semiconductor packages comprises a first radio communication element for transmitting and receiving a signal between the semiconductor chips in the plurality of semiconductor packages by radio communication, and

the first radio communication element is constituted independently of the semiconductor chip.

[2] (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises a resin portion for sealing the semiconductor chip.

[3] (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises a resin portion for sealing the semiconductor chip, and

the first radio communication element is provided inside or on a surface of the resin portion.

[4] (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises a shielding layer for blocking an electromagnetic wave.

[5] (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises a shielding layer for blocking an electromagnetic wave in a part of a surface of the first radio communication element.

[6] (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises an interposer on which the semiconductor chip is placed.

[7] (Original) The module according to claim 1, wherein each of the plurality of semiconductor packages further comprises an interposer on which the semiconductor chip is placed, and

the first radio communication element is provided inside or on a surface of the interposer.

[8] (Original) The module according to claim 1, wherein the substrate is a single-sided substrate obtained by forming a conductor pattern on only one principal surface of a base or a double-sided substrate obtained by forming a conductor pattern on both principal surfaces of the base, and

each of the plurality of semiconductor packages is mounted on the conductor pattern.

[9] (Original) The module according to claim 8, wherein the conductor pattern is constituted by at least one terminal selected from the group consisting of a power source terminal and a ground terminal.

[10] (Original) The module according to claim 1, further comprising a second radio communication element for transmitting and receiving a signal with respect to at least one of the first radio communication elements included respectively in the plurality of semiconductor packages by radio communication, and an electronic component electrically connected to the second radio communication element.

[11] (Currently amended) A mounted structure comprising ~~the module according to~~  
~~claim 1~~ a module comprising:

a substrate; and  
a plurality of semiconductor packages, each comprising a semiconductor chip,  
mounted on the substrate;  
wherein each of the plurality of semiconductor packages comprises a first radio  
communication element for transmitting and receiving a signal between the  
semiconductor chips in the plurality of semiconductor packages by radio communication,  
and  
the first radio communication element is constituted independently of the  
semiconductor chip.